MOSFETs Silicon P-Channel MOS (U-MOSVI)

# **TPCP8107**

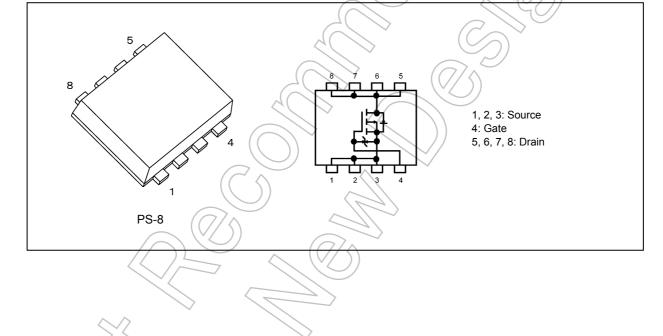
### 1. Applications

- · Motor Drivers
- · Mobile Equipment

#### 2. Features

- (1) AEC-Q101 qualified
- (2) Small, thin package
- (3) Small gate charge:  $Q_{SW} = 14.0 \text{ nC (typ.)}$
- (4) Low drain-source on-resistance:  $R_{DS(ON)} = 13.9 \text{ m}\Omega$  (typ.) ( $V_{GS} = 10 \text{ V}$ )
- (5) Low leakage current:  $I_{\rm DSS}$  = -10  $\mu A$  (max) (V\_{\rm DS} = -40 V)
- (6) Enhancement mode:  $V_{th} = -2 \text{ to } -3 \text{ V } (V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA})$

### 3. Packaging and Internal Circuit



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Rev.4.0



## 4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

Characteris	Symbol	Rating	Unit		
Drain-source voltage			$V_{DSS}$	-40	V
Gate-source voltage			V <sub>GSS</sub>	-20/+10	
Drain current (DC)		(Note 1)	I <sub>D</sub>	-8	Α
Drain current (pulsed)		(Note 1)	I <sub>DP</sub>	-32	
Power dissipation	(t = 5 s)	(Note 2)	$P_{D}$	2.01	W
Power dissipation	(t = 5 s)	(Note 3)	P <sub>D</sub>	1	W
Single-pulse avalanche energy		(Note 4)	EAS	145.8	mJ
Avalanche current		,	I <sub>AR</sub>	8-	Α
Channel temperature		(Note 5)	T <sub>ch</sub>	175	°C
Storage temperature	·	(Note 5)	T <sub>stg</sub>	-55 to 175	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

### 5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-ambient thermal resistance (t = 5 s) (Note 2)	R <sub>th(ch-a)</sub>	74.6	°C/W
Channel-to-ambient thermal resistance (t = 5 s) (Note 3)		150	

Note 1: Ensure that the channel temperature does not exceed 175°C.

Note 2: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 3: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 4:  $V_{DD}$  = -25 V,  $T_{ch}$  = 25°C (initial), L = 2,366 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = -8 A

Note 5: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.



Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

FR-4

(Unit: mm)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



#### 6. Electrical Characteristics

## 6.1. Static Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = -16/+10 V, V <sub>DS</sub> = 0 V	_	_	±10	μА
Drain cut-off current	I <sub>DSS</sub>	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}$	7	_	-10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 0 V	-40	_		V
Drain-source breakdown voltage (Note 6)	V <sub>(BR)DSX</sub>	I <sub>D</sub> = -10 mA, V <sub>GS</sub> = 10 V	-30	) /~	_	
Gate threshold voltage	$V_{th}$	V <sub>DS</sub> = -10 V, I <sub>D</sub> = -1 mA	-2	-2.5	-3	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = -6 V, I <sub>D</sub> = -4 A	/ <del>(</del> )	16.8	26.8	mΩ
		V <sub>GS</sub> = -10 V, I <sub>D</sub> = -4 A		13.9	18	

Note 6: If a reverse bias is applied between gate and source, this device enters V<sub>(BR)DSX</sub> mode. Note that the drain-source breakdown voltage is lowered in this mode.

# 6.2. Dynamic Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		2160	) —	pF
Reverse transfer capacitance	C <sub>rss</sub>		<u> </u>	238	_	
Output capacitance	C <sub>oss</sub>			292		
Switching time (rise time)	t <sub>r</sub>	See Figure 6.2.1.		11	_	ns
Switching time (turn-on time)	t <sub>on</sub>		$\wedge$ $-$	29	_	
Switching time (fall time)	t <sub>f</sub>		<u>リー</u>	35		
Switching time (turn-off time)	t <sub>off</sub>		_	150	_	

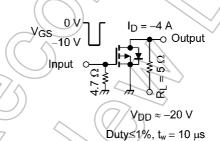


Fig. 6.2.1 Switching Time Test Circuit

# 6.3. Gate Charge Characteristics ( $T_a = 25^{\circ}$ C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx -32 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -8 \text{ A}$	_	44.6	_	nC
Gate-source charge 1	Q <sub>gs1</sub>		_	5.7	_	
Gate-drain charge	Q <sub>gd</sub>		_	13.1		
Gate switch charge	Q <sub>SW</sub>		_	14.0	_	

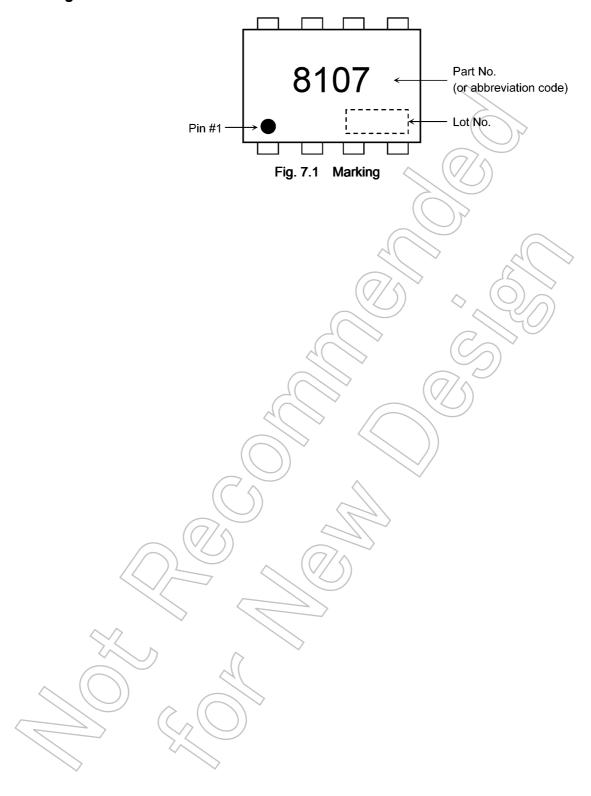
# 6.4. Source-Drain Characteristics ( $T_a = 25^{\circ}C$ unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed)	(Note 7)	I <sub>DRP</sub>	_	_	_	-32	Α
Diode forward voltage		$V_{DSF}$	I <sub>DR</sub> = -8 A, V <sub>GS</sub> = 0 V	_		1.2	V

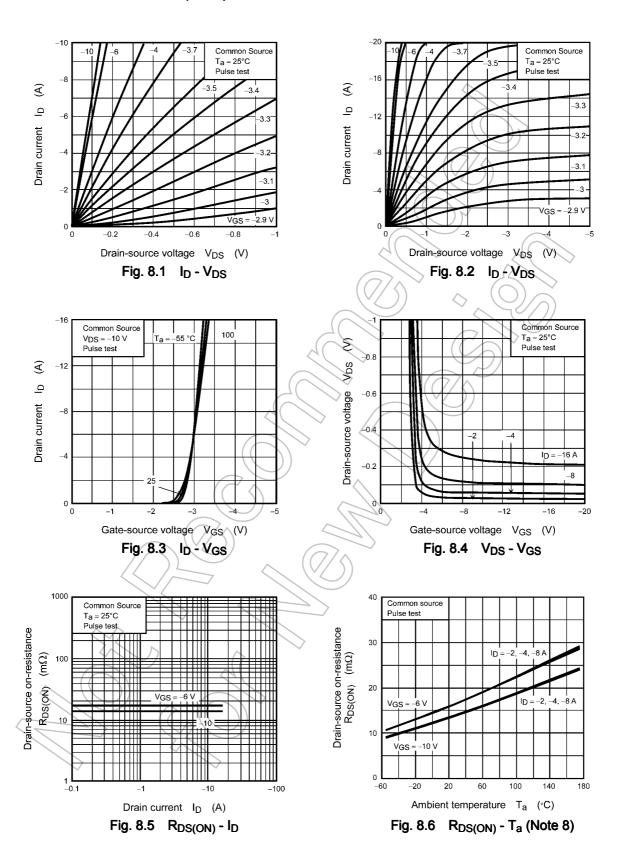
Note 7: Ensure that the channel temperature does not exceed 175°C.



## 7. Marking



### 8. Characteristics Curves (Note)



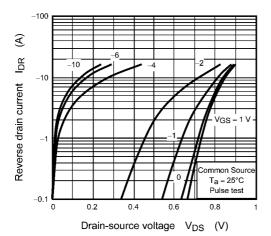


Fig. 8.7 IDR - VDS

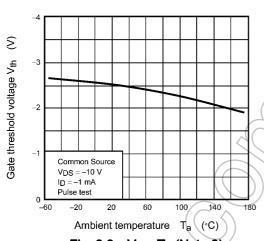


Fig. 8.9 V<sub>th</sub> - T<sub>a</sub> (Note 8)

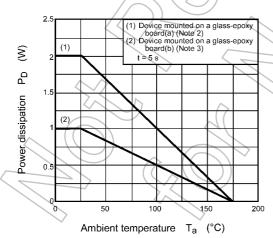


Fig. 8.11 P<sub>D</sub> - T<sub>a</sub> (Guaranteed Maximum) (Note 8)

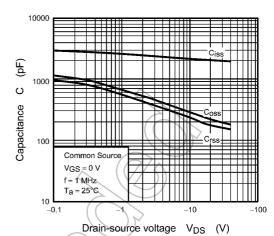


Fig. 8.8 Capacitance - V<sub>DS</sub>

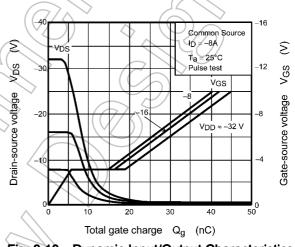


Fig. 8.10 Dynamic Input/Output Characteristics

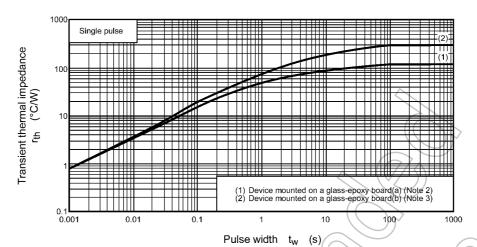


Fig. 8.12 r<sub>th</sub> - t<sub>w</sub> (Guaranteed Maximum)

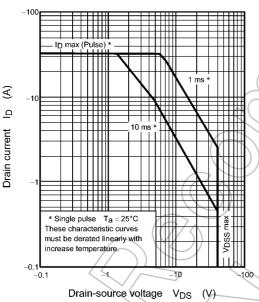


Fig. 8.13 Safe Operating Area (Guaranteed Maximum)

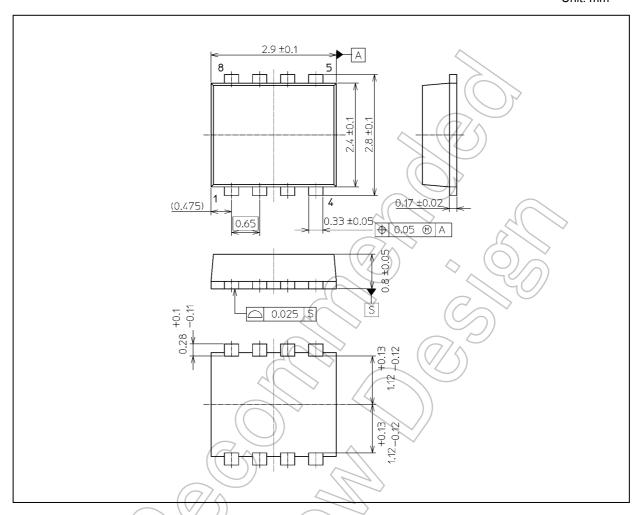
Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Note 8: The definitions of the absolute maximum channel and storage temperatures are qualified per AEC-Q101.

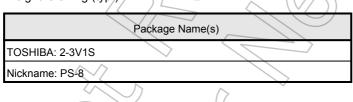


## **Package Dimensions**

Unit: mm



Weight: 0.017 g (typ.)







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